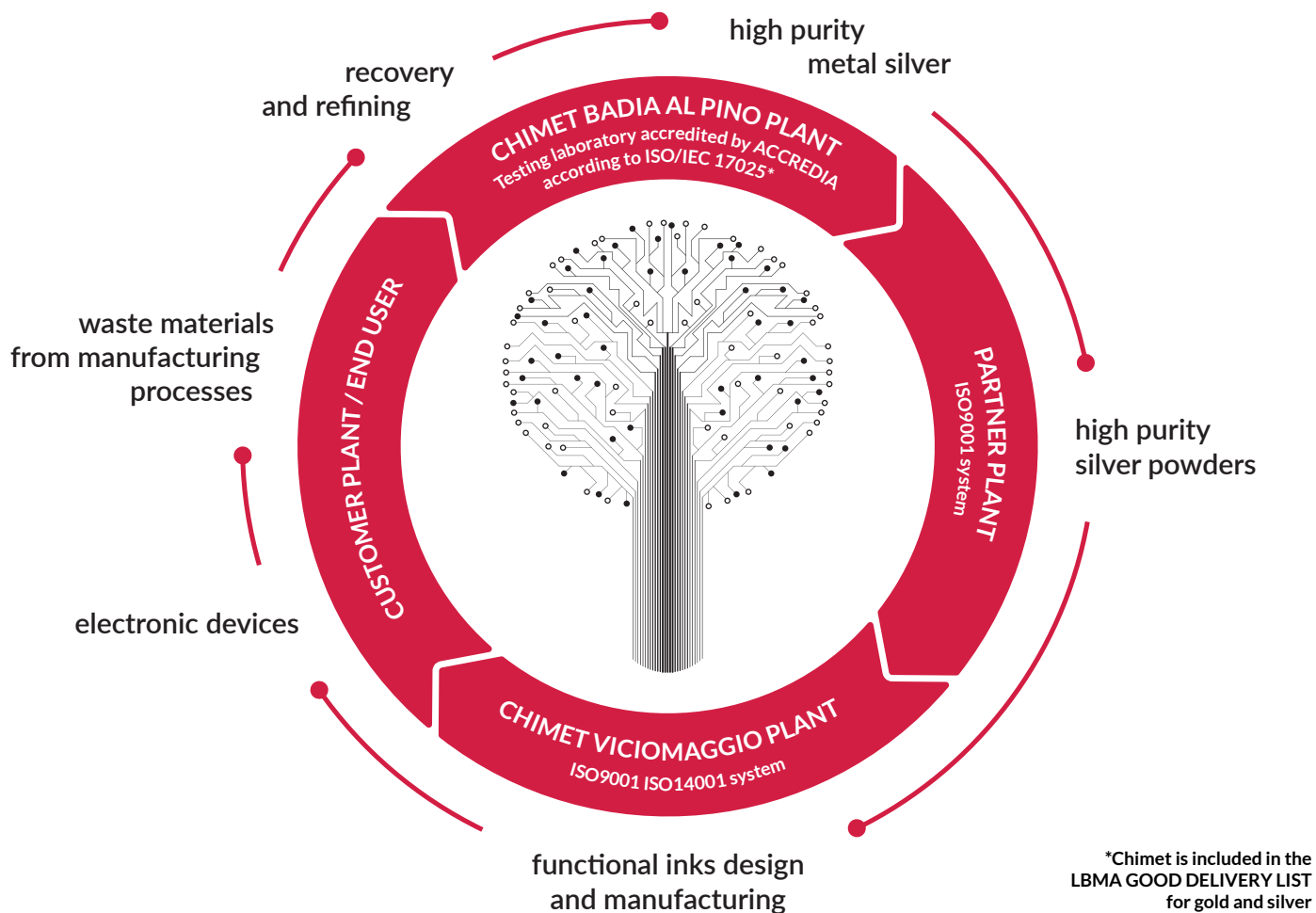




FUNCTIONAL INKS APPLICATION

flexible electronics	silver based	conductivity, flexibility, excellent printability	AG515EI	<15 mΩ/□/mil
		high conductivity, flexibility, excellent printability	AG510EI	<10 mΩ/□/mil
		conductivity, flexibility, fine line capability	AG511EI	<20 mΩ/□/mil
		superior compatibility with solvent sensitive substrates	AG580EI	<20 mΩ/□/mil
	carbon based	moisture resistant, abrasion resistant, flexible	C800EI	<40 Ω/□/mil
	acrylic based	superior adhesion and flexibility, dielectric ink	D110EI	N/A
		transparent, adhesion, flexibility, dielectric ink	D160EI	N/A
	epoxy based	dispensable, durable, 90°C cure	AG910EI	<5 x 10 ⁻⁴ Ω•cm

soft electronics (elastic materials)	silver based	TPU compatible, excellent printability, conductive	AG520EI	<60 mΩ/□/mil
	carbon based	TPU compatible, excellent printability, resistive	C820EI	<200 Ω/□/mil
	filler based	thermic elastic cover	D220EI	N/A
	acrylic based	protective ink with no additional stiffness on TPU multilayer	D181EI	N/A

In-Mold electronics (thermoformable materials)	silver based	high thermoformability, conductive	AG550EI	<60 mΩ/□/mil
		medium thermoformability, high conductivity	AG555EI	<20 mΩ/□/mil
	carbon based	high thermoformability, abrasion and moisture resistant	C850EI	<300 Ω/□/mil
	acrylic based	white durable thermic dielectric ink	D260EI	N/A
	epoxy based	dispensable, solventless, 90°C cure	AG903EI	<5 x 10 ⁻⁴ Ω•cm